

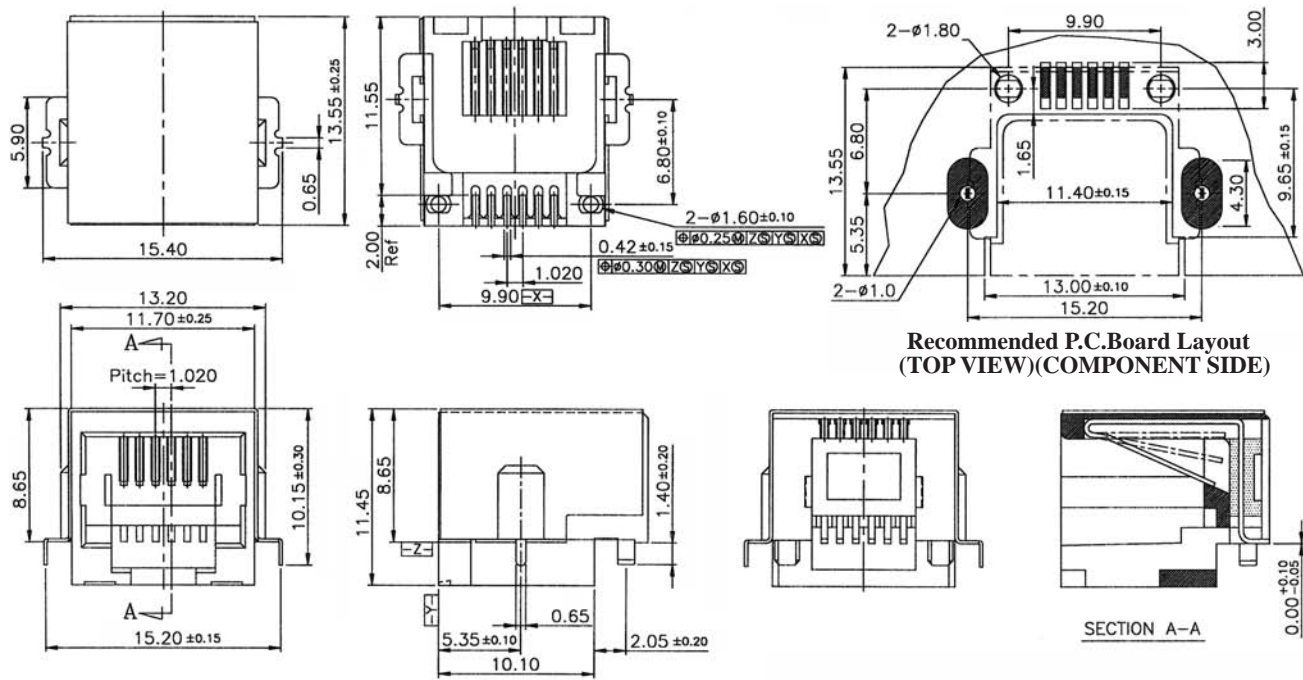
SIDE ENTRY EMBEDDED MODULAR SMT JACK 6P PROFILE=11.45MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
All materials must be RoHS compliant.



Recommended P.C. Board Layout
(TOP VIEW)(COMPONENT SIDE)

ORDERING INFORMATION:

P/N M J 4 Z - $\frac{x}{1}$ $\frac{x}{2}$ $\frac{x}{3}$ B - $\frac{x}{3}$

- NO. OF POSITIONS & CONTACTS:
 "66" 6P6C
 "64" 6P4C
- CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD
- PACKAGE OPTION:
 " " TRAY
 "R" TAPE & REEL

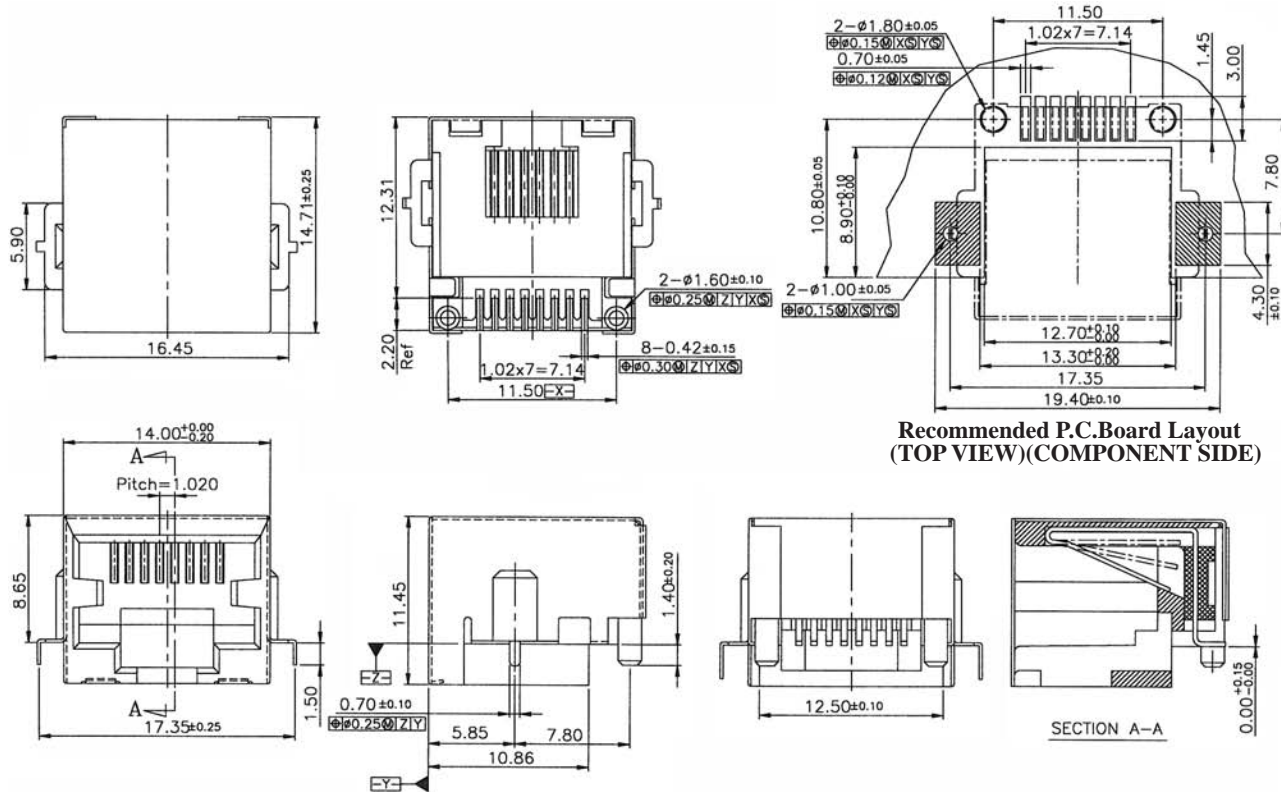
SIDE ENTRY EMBEDDED MODULAR SMT JACK 8P PROFILE=11.45MM (FULLY SHIELDED)

SPECIFICATIONS

Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: Nylon (UL 94V-0)
Soldering Temperature: 260°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
All materials must be RoHS compliant.



ORDERING INFORMATION:

P/N MJ4Z - $\frac{88}{1} \times \frac{B}{2} - \frac{x}{3}$

1. NO. OF POSITIONS & CONTACTS:
"88" 8P8C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD
"E" GOLD FLASH
3. PACKAGE OPTION:
" " TRAY
"R" TAPE & REEL